IPC ASSOCIATION CONNE ELECTRONICS INDUS	© Copyright 2005, IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typhttp://www.ipc.org/IPC-175x Distribute										als and Mf	g Infor	rmation		
Supplier Info	rmation				•											
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*				
onsemi												2025-07-10				
Contact Name			Title - Contact			I	Phone - Contact*					Email - Contact*				
Product-Env-Sto	ewards	Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com					
uthorized Repr	resentative*	Title - Representative			I	Phone - Representative*				Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com					
Requ	ester Item Number	NCP170BMX180TCG 150mA LDC		em Number Mfr Item Name			Effective Dat	te Versio	Version Ma		Manufacturing Site		/eight*	* [UOM	Unit Type
				150mA LDO, Ul State, Vout=1.8V			2025-07-10 PI		РНМ		1	1.42 mg		mg	Each	
Ianufacturi i	ng Proccess Informat	ion														
Termi	nal Plating / Grid Array Mat	Plating / Grid Array Material		Terminal Base Alloy J		0-020 MSL Rating		Peak Process Body Temperature		re Max Time at Peak Temper		Temperatu	ature Number of Reflow Cycles		les	
Precio Sn)			CU Alloy 1		1		260		С		30 seco		ls 3			
Comments												-				
vel 1 - maximu	m time at peak temperatui	re during so	ldering is 10-3	0 seconds		·	·			·		·			·	
or more inform	ation regarding material c	omposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detail	led						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substa	ances per the definition above	Supplier Ac	ceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructional Complete all of the required	fields on all neggs of this form. Calcut th		a duan dawn. This will display the signature on	a Digitally sign	the declaration (if recurined by the						
Instructions: Complete all of the required Requester) and click on Submit Form to			e drop-down. This will display the signature ar	ea. Digitally sign	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.09	mg	Supplier	Silicon (Si)	7440-21-3		0.09	mg
Die Attach Epoxy	0.13	mg		Epoxy resin	proprietary data		0.0845	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.0455	mg
Lead Frame	0.58	mg	Supplier	Magnesium (Mg)	7439-95-4		0.0009	mg
			Supplier	Silicon (Si)	7440-21-3		0.0038	mg
			В	Nickel (Ni)	7440-02-0		0.0174	mg
			Supplier	Copper (Cu)	7440-50-8		0.558	mg
Mold Compound-Black	0.6	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.048	mg
			Supplier	Carbon Black (C)	1333-86-4		0.003	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.012	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.519	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.018	mg
Plating	0.004	mg	Supplier	Palladium (Pd)	7440-05-3		0.0001	mg
			В	Nickel (Ni)	7440-02-0		0.0035	mg
			Supplier	Gold (Au)	7440-57-5		0.0004	mg
Wire Bond	0.016	mg	Supplier	Palladium (Pd)	7440-05-3		0.0005	mg
			Supplier	Gold (Au)	7440-57-5		0.0001	mg
			Supplier	Copper (Cu)	7440-50-8		0.0154	mg